

[METHOD OF AVOIDING DIELECTRIC LAYER DETERIOATION WITH A LOW DIELECTRIC CONSTANT DURING A STRIPPING PROCESS]

Abstract of Disclosure

A low k dielectric layer is formed on a surface of a substrate of a semiconductor wafer. Then, a surface treatment is performed to the low k dielectric layer to form a passivation layer on a surface of the low k dielectric layer. A patterned photoresist layer is formed over the surface of the semiconductor wafer. The patterned photoresist layer is then used as a hard mask to perform an etching process on the low k dielectric layer. Finally, a stripping process is performed to remove the patterned photoresist layer. The passivation layer is used to prevent deterioration of the dielectric characteristic of the low k dielectric layer during the stripping process.

Variable	Mean	SD	Min	Max
Age	38.5	10.2	22	65
Gender	0.5	0.5	0	1
Marital Status	0.7	0.5	0	1
Education	12.5	1.5	9	16
Income	3500	1500	1000	8000
Health Status	0.8	0.4	0	1
Exercise Frequency	2.5	1.5	0	5
Stress Level	4.5	1.5	1	7
Sleep Quality	3.5	1.5	1	6
Dietary Habits	2.5	1.5	0	5
Work-Life Balance	3.5	1.5	1	6
Family Support	4.5	1.5	1	7
Community Involvement	2.5	1.5	0	5
Personal Growth	3.5	1.5	1	6
Life Satisfaction	4.5	1.5	1	7
Overall Well-being	4.5	1.5	1	7